

SPM® MODULE DESIGN GUIDE

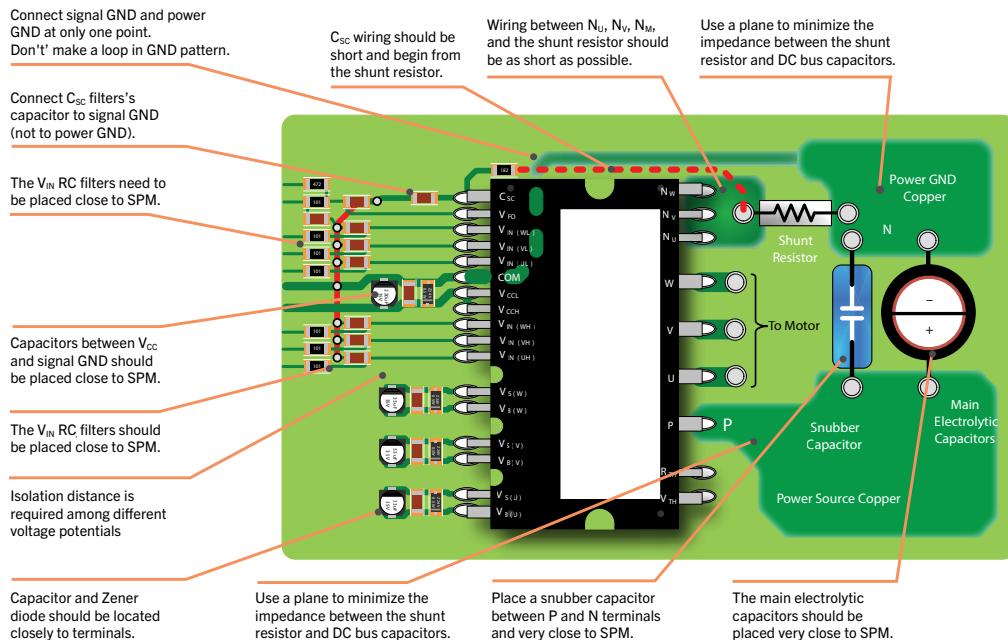
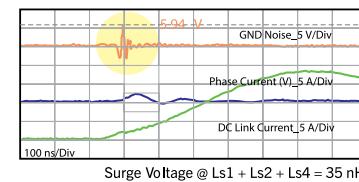
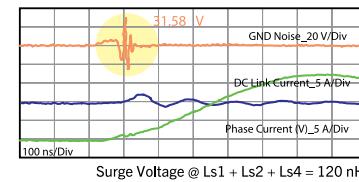
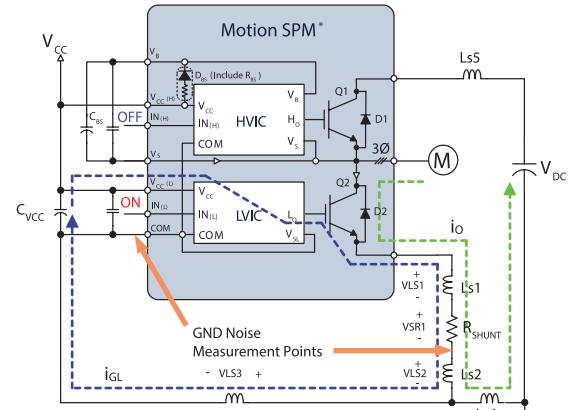
Fairchild Semiconductor has the integrated and discrete devices for your consumer and industrial motor control applications.

Our solutions deliver high integration, power efficiency, system reliability and functionality while reducing engineering development time.

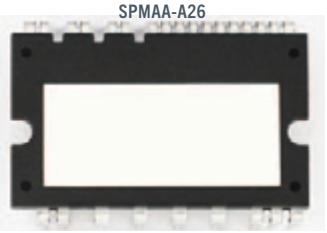
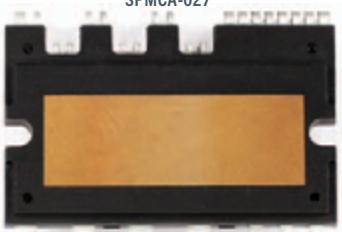
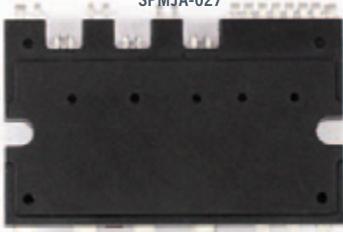
Achieve High Efficiency and System Reliability with These Design Guidelines

Recommendations for better board design provide significant reduction in electrical over-stress (EOS), consequently achieving improved system reliability without sacrificing efficiency.

- Minimized stray inductance ($L_{S1} + L_{S2} + L_{S4}$) can reduce ground noise (surge voltage)
- Non-inductive resistor should be used for shunt resistor
- Connect the power ground terminal with the signal ground at a single point, using non-loop ground pattern



MOTION SPM® MODULE PACKAGE REFERENCE

Dimensions (mm xmm)	Features	Packages 1:1 Ratio		
SPM 5 Series (29 x 12 x 3.1) Substrate: Full-pack Lead Options: Different lead options available	<ul style="list-style-type: none"> • 500 V/250 V • UVLO, BSD, TSU • MOSFETs solution 			
SPM 45 Series (39 x 23 x 4.5) Substrate: Ceramic Lead Options: Different lead options available	<ul style="list-style-type: none"> • 600 V, 5-20 A • NTC, UVLO, OCP, BSD • IGBTs solution • PFC SPM solution is also available in SPM 45 package 			
SPM 3 Series (44 x 26.8 x 5.5) Substrate: DBC, full-pack	<ul style="list-style-type: none"> • 600 V, 5-30 A • UVLO, OCP, BSD, TSD • IGBTs solution is also available in SPM 3 package 			
SPM 2 Series (60 x 31 x 7.2) Substrate: DBC	<ul style="list-style-type: none"> • 600 V, ~75 A • NTC, UVLO, OCP • Current sensing with sensing IGBTs • IGBTs solution • PFC SPM solution is also available in SPM 2 package 			
SPM 1 Series (96 x 55 x 7.2) Substrate: DBC	<ul style="list-style-type: none"> • 600 V, ~75 A • NTC, UVLO, OCP • IGBTs solution • PFC and inverter merged solution is also available in SPM 1 package 			

Description of Integrated Functions in SPM Solution - BSD: Boot Strap Diode, OCP: Over Current Protection, TSD: Thermal Shut Down, TSU: Thermal Sensing Unit, NTC: Negative Temperature Coefficient Thermistor



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